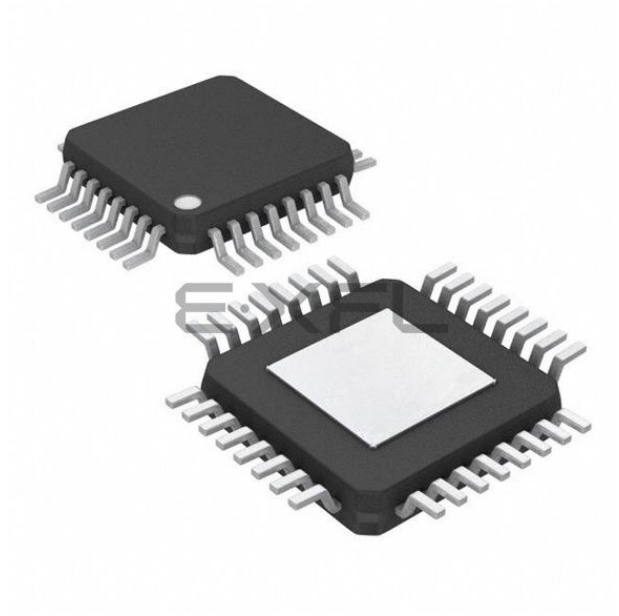

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	I²C, LINbus, SPI, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	26
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	1.62V ~ 3.6V
Data Converters	A/D 10x12b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-TQFP
Supplier Device Package	32-TQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atsamd21e17a-au

        - Up to four compare channels with optional complementary output
        - Generation of synchronized pulse width modulation (PWM) pattern across port pins
        - Deterministic fault protection, fast decay and configurable dead-time between complementary output
        - Dithering that increase resolution with up to 5 bit and reduce quantization error
    - 32-bit Real Time Counter (RTC) with clock/calendar function
    - Watchdog Timer (WDT)
    - CRC-32 generator
    - One full-speed (12Mbps) Universal Serial Bus (USB) 2.0 interface
        - Embedded host and device function
        - Eight endpoints
    - Up to six Serial Communication Interfaces (SERCOM), each configurable to operate as either:
        - USART with full-duplex and single-wire half-duplex configuration
        - I2C up to 3.4MHz
        - SPI
        - LIN slave
    - One two-channel Inter-IC Sound (I^2S) interface
    - One 12-bit, 350ksps Analog-to-Digital Converter (ADC) with up to 20 channels
        - Differential and single-ended input
        - 1/2x to 16x programmable gain stage
        - Automatic offset and gain error compensation
        - Oversampling and decimation in hardware to support 13-, 14-, 15- or 16-bit resolution
    - 10-bit, 350ksps Digital-to-Analog Converter (DAC)
    - Two Analog Comparators (AC) with window compare function
    - Peripheral Touch Controller (PTC)
        - 256-Channel capacitive touch and proximity sensing
- I/O
    - Up to 52 programmable I/O pins
- Drop in compatible with SAM D20
- Packages
    - 64-pin TQFP, QFN, UFBGA
    - 48-pin TQFP, QFN, WLCSP
    - 32-pin TQFP, QFN, WLCSP
- Operating Voltage
    - 1.62V – 3.63V

1. Description

The SAM D21 is a series of low-power microcontrollers using the 32-bit ARM® Cortex®-M0+ processor, and ranging from 32- to 64-pins with up to 256KB Flash and 32KB of SRAM. The SAM D21 operate at a maximum frequency of 48MHz and reach 2.46 CoreMark/MHz. They are designed for simple and intuitive migration with identical peripheral modules, hex compatible code, identical linear address map and pin compatible migration paths between all devices in the product series. All devices include intelligent and flexible peripherals, Event System for inter-peripheral signaling, and support for capacitive touch button, slider and wheel user interfaces.

The SAM D21 provide the following features: In-system programmable Flash, twelve-channel direct memory access (DMA) controller, 12 channel Event System, programmable interrupt controller, up to 52 programmable I/O pins, 32-bit real-time clock and calendar, up to five 16-bit Timer/Counters (TC) and three 24-bit Timer/Counters for Control (TCC), where each TC can be configured to perform frequency and waveform generation, accurate program execution timing or input capture with time and frequency measurement of digital signals. The TCs can operate in 8- or 16-bit mode, selected TCs can be cascaded to form a 32-bit TC, and three timer/counters have extended functions optimized for motor, lighting and other control applications. The series provide one full-speed USB 2.0 embedded host and device interface; up to six Serial Communication Modules (SERCOM) that each can be configured to act as an USART, UART, SPI, I^2C up to 3.4MHz, SMBus, PMBus, and LIN slave; two-channel I^2S interface; up to twenty-channel 350ksps 12-bit ADC with programmable gain and optional oversampling and decimation supporting up to 16-bit resolution, one 10-bit 350ksps DAC, two analog comparators with window mode, Peripheral Touch Controller supporting up to 256 buttons, sliders, wheels and proximity sensing; programmable Watchdog Timer, brown-out detector and power-on reset and two-pin Serial Wire Debug (SWD) program and debug interface.

All devices have accurate and low-power external and internal oscillators. All oscillators can be used as a source for the system clock. Different clock domains can be independently configured to run at different frequencies, enabling power saving by running each peripheral at its optimal clock frequency, and thus maintaining a high CPU frequency while reducing power consumption.

The SAM D21 have two software-selectable sleep modes, idle and standby. In idle mode the CPU is stopped while all other functions can be kept running. In standby all clocks and functions are stopped expect those selected to continue running. The device supports SleepWalking. This feature allows the peripheral to wake up from sleep based on predefined conditions, and thus allows the CPU to wake up only when needed, e.g. when a threshold is crossed or a result is ready. The Event System supports synchronous and asynchronous events, allowing peripherals to receive, react to and send events even in standby mode.

The Flash program memory can be reprogrammed in-system through the SWD interface. The same interface can be used for non-intrusive on-chip debug of application code. A boot loader running in the device can use any communication interface to download and upgrade the application program in the Flash memory.

The SAM D21 microcontrollers are supported with a full suite of program and system development tools, including C compilers, macro assemblers, program debugger/simulators, programmers and evaluation kits.

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD21E16A-AU	64K	8K	TQFP32	Tray
ATSAMD21E16A-AUT				Tape & Reel
ATSAMD21E16A-AF				Tray
ATSAMD21E16A-AFT				Tape & Reel
ATSAMD21E16A-MU			QFN32	Tray
ATSAMD21E16A-MUT				Tape & Reel
ATSAMD21E16A-MF				Tray
ATSAMD21E16A-MFT				Tape & Reel
ATSAMD21E17A-AU	128K	16K	TQFP32	Tray
ATSAMD21E17A-AUT				Tape & Reel
ATSAMD21E17A-AF				Tray
ATSAMD21E17A-AFT				Tape & Reel
ATSAMD21E17A-MU			QFN32	Tray
ATSAMD21E17A-MUT				Tape & Reel
ATSAMD21E17A-MF				Tray
ATSAMD21E17A-MFT				Tape & Reel
ATSAMD21E18A-AU	256K	32K	TQFP32	Tray
ATSAMD21E18A-AUT				Tape & Reel
ATSAMD21E18A-AF				Tray
ATSAMD21E18A-AFT				Tape & Reel
ATSAMD21E18A-MU			QFN32	Tray
ATSAMD21E18A-MUT				Tape & Reel
ATSAMD21E18A-MF				Tray
ATSAMD21E18A-MFT				Tape & Reel

Table 3-2. Device Variant B

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD21E15B-AU	32K	4K	TQFP32	Tray
ATSAMD21E15B-AUT				Tape & Reel
ATSAMD21E15B-AF				Tray
ATSAMD21E15B-AFT				Tape & Reel
ATSAMD21E15B-MU			QFN32	Tray
ATSAMD21E15B-MUT				Tape & Reel
ATSAMD21E15B-MF				Tray
ATSAMD21E15B-MFT				Tape & Reel
ATSAMD21E15B-UUT			WLCSP35 (GJR)	Tape & Reel
ATSAMD21E16B-AU	64K	8K	TQFP32	Tray
ATSAMD21E16B-AUT				Tape & Reel
ATSAMD21E16B-AF				Tray
ATSAMD21E16B-AFT				Tape & Reel
ATSAMD21E16B-MU			QFN32	Tray
ATSAMD21E16B-MUT				Tape & Reel
ATSAMD21E16B-MF				Tray
ATSAMD21E16B-MFT				Tape & Reel
ATSAMD21E16B-UUT	64K	8K	WLCSP35 (GJR)	Tape & Reel

Table 3-3. Device Variant C

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD21E15C-UUT	32K	4K	WLCSP35 (GJS)	Tape & Reel
ATSAMD21E16C-UUT	64K	8K	WLCSP35 (GJS)	Tape & Reel

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD21G18A-AU	256K	32K	TQFP48	Tray
ATSAMD21G18A-AUT				Tape & Reel
ATSAMD21G18A-AF				Tray
ATSAMD21G18A-AFT				Tape & Reel
ATSAMD21G18A-MU			QFN48	Tray
ATSAMD21G18A-MUT				Tape & Reel
ATSAMD21G18A-MF				Tray
ATSAMD21G18A-MFT				Tape & Reel
ATSAMD21G18A-UUT			WLCSP45	Tape & Reel

Table 3-5. Device Variant B

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD21G15B-AU	32K	4K	TQFP48	Tray
ATSAMD21G15B-AUT				Tape & Reel
ATSAMD21G15B-AF				Tray
ATSAMD21G15B-AFT				Tape & Reel
ATSAMD21G15B-MU			QFN48	Tray
ATSAMD21G15B-MUT				Tape & Reel
ATSAMD21G15B-MF				Tray
ATSAMD21G15B-MFT				Tape & Reel
ATSAMD21G16B-AU	64K	8K	TQFP48	Tray
ATSAMD21G16B-AUT				Tape & Reel
ATSAMD21G16B-AF				Tray
ATSAMD21G16B-AFT				Tape & Reel
ATSAMD21G16B-MU			QFN48	Tray
ATSAMD21G16B-MUT				Tape & Reel
ATSAMD21G16B-MF				Tray
ATSAMD21G16B-MFT				Tape & Reel

3.3 SAM D21J

Table 3-6. Device Variant A

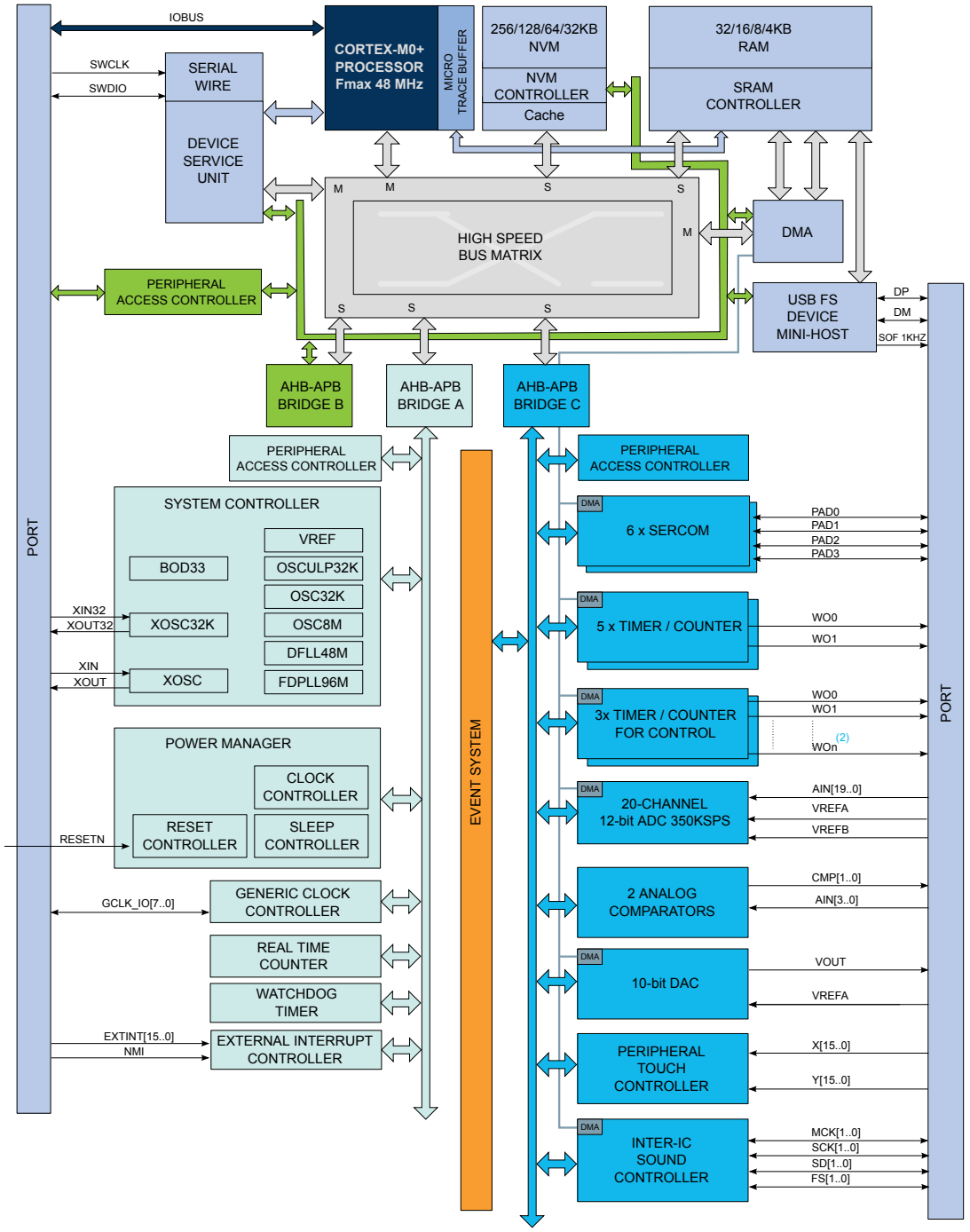
Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD21J15A-AU	32K	4K	TQFP64	Tray
ATSAMD21J15A-AUT				Tape & Reel
ATSAMD21J15A-AF				Tray
ATSAMD21J15A-AFT				Tape & Reel
ATSAMD21J15A-MU			QFN64	Tray
ATSAMD21J15A-MUT				Tape & Reel
ATSAMD21J15A-MF				Tray
ATSAMD21J15A-MFT				Tape & Reel
ATSAMD21J16A-AU	64K	8K	TQFP64	Tray
ATSAMD21J16A-AUT				Tape & Reel
ATSAMD21J16A-AF				Tray
ATSAMD21J16A-AFT				Tape & Reel
ATSAMD21J16A-MU			QFN64	Tray
ATSAMD21J16A-MUT				Tape & Reel
ATSAMD21J16A-MF				Tray
ATSAMD21J16A-MFT				Tape & Reel
ATSAMD21J16A-CU			UFBGA64	Tray
ATSAMD21J16A-CUT				Tape & Reel
ATSAMD21J17A-AU	128K	16K	TQFP64	Tray
ATSAMD21J17A-AUT				Tape & Reel
ATSAMD21J17A-AF				Tray
ATSAMD21J17A-AFT				Tape & Reel
ATSAMD21J17A-MU			QFN64	Tray
ATSAMD21J17A-MUT				Tape & Reel
ATSAMD21J17A-MF				Tray
ATSAMD21J17A-MFT				Tape & Reel
ATSAMD21J17A-CU			UFBGA64	Tray
ATSAMD21J17A-CUT				Tape & Reel

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD21J18A-AU	256K	32K	TQFP64	Tray
ATSAMD21J18A-AUT				Tape & Reel
ATSAMD21J18A-AF				Tray
ATSAMD21J18A-AFT				Tape & Reel
ATSAMD21J18A-MU			QFN64	Tray
ATSAMD21J18A-MUT				Tape & Reel
ATSAMD21J18A-MF				Tray
ATSAMD21J18A-MFT				Tape & Reel
ATSAMD21J18A-CU			UFBGA64	Tray
ATSAMD21J18A-CUT				Tape & Reel

Table 3-7. Device Variant B

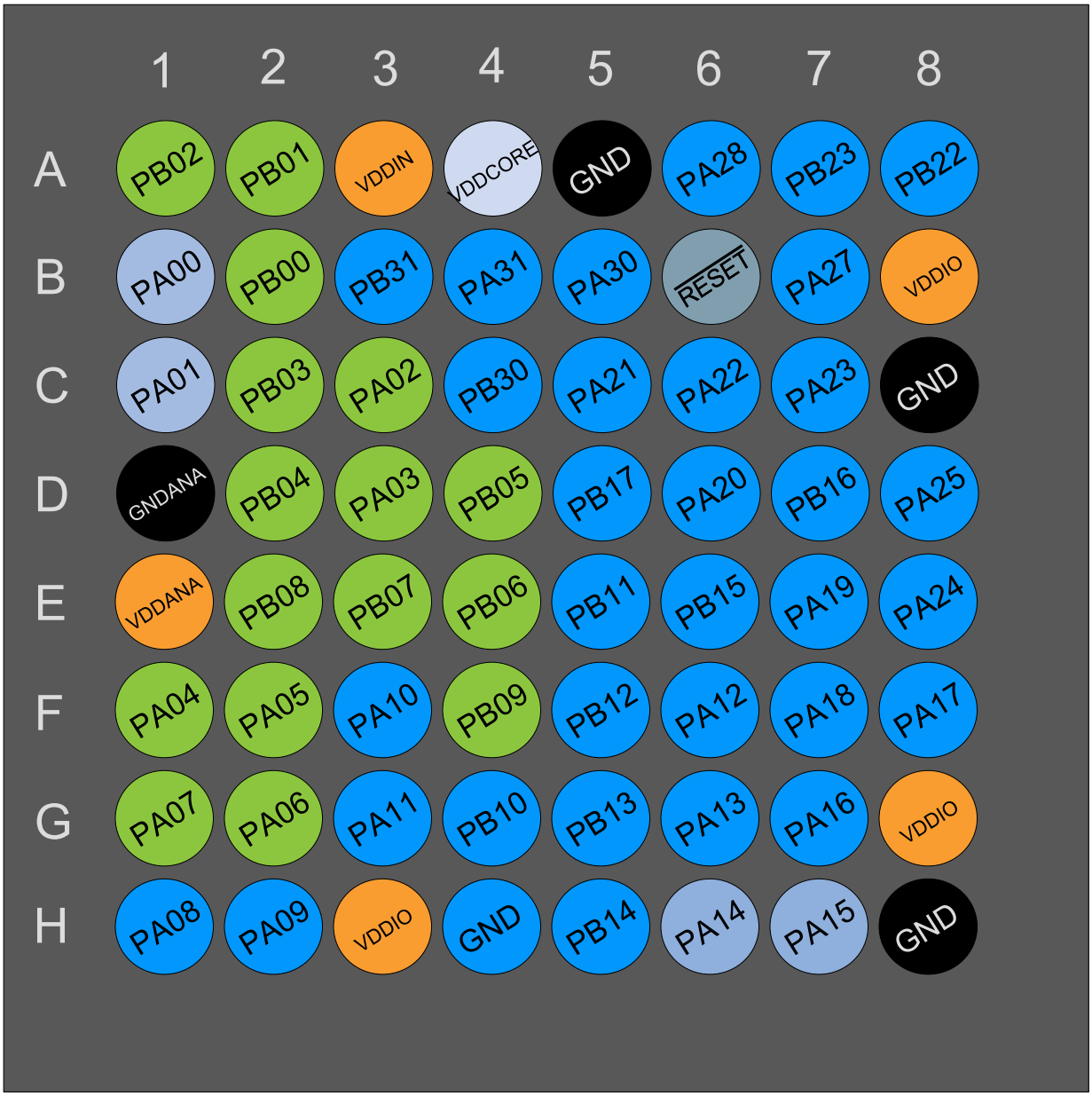
Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD21J15B-AU	32K	4K	TQFP64	Tray
ATSAMD21J15B-AUT				Tape & Reel
ATSAMD21J15B-AF				Tray
ATSAMD21J15B-AFT				Tape & Reel
ATSAMD21J15B-MU			QFN64	Tray
ATSAMD21J15B-MUT				Tape & Reel
ATSAMD21J15B-MF				Tray
ATSAMD21J15B-MFT				Tape & Reel
ATSAMD21J16B-AU	64K	8K	TQFP64	Tray
ATSAMD21J16B-AUT				Tape & Reel
ATSAMD21J16B-AF				Tray
ATSAMD21J16B-AFT				Tape & Reel
ATSAMD21J16B-MU			QFN64	Tray
ATSAMD21J16B-MUT				Tape & Reel
ATSAMD21J16B-MF				Tray
ATSAMD21J16B-MFT				Tape & Reel
ATSAMD21J16B-CU			UFBGA64	Tray
ATSAMD21J16B-CUT				Tape & Reel

4. Block Diagram



1. Some products have different number of SERCOM instances, Timer/Counter instances, PTC signals and ADC signals. Refer to the Configuration Summary for details.
2. The three TCC instances have different configurations, including the number of Waveform Output (WO) lines. Refer to the TCC Configuration for details.

5.1.2 UFBGA64



- DIGITAL PIN
- ANALOG PIN
- OSCILLATOR
- GROUND
- INPUT SUPPLY
- REGULATED OUTPUT SUPPLY
- RESET PIN

Peripheral Source	NVIC Line
AC – Analog Comparator	24
DAC – Digital-to-Analog Converter	25
PTC – Peripheral Touch Controller	26
I2S - Inter IC Sound	27

7.3 Micro Trace Buffer

7.3.1 Features

- Program flow tracing for the Cortex-M0+ processor
- MTB SRAM can be used for both trace and general purpose storage by the processor
- The position and size of the trace buffer in SRAM is configurable by software
- CoreSight compliant

7.3.2 Overview

When enabled, the MTB records changes in program flow, reported by the Cortex-M0+ processor over the execution trace interface shared between the Cortex-M0+ processor and the CoreSight MTB-M0+. This information is stored as trace packets in the SRAM by the MTB. An off-chip debugger can extract the trace information using the Debug Access Port to read the trace information from the SRAM. The debugger can then reconstruct the program flow from this information.

The MTB simultaneously stores trace information into the SRAM, and gives the processor access to the SRAM. The MTB ensures that trace write accesses have priority over processor accesses.

The execution trace packet consists of a pair of 32-bit words that the MTB generates when it detects the processor PC value changes non-sequentially. A non-sequential PC change can occur during branch instructions or during exception entry. See the CoreSight MTB-M0+ Technical Reference Manual for more details on the MTB execution trace packet format.

Tracing is enabled when the MASTER.EN bit in the Master Trace Control Register is 1. There are various ways to set the bit to 1 to start tracing, or to 0 to stop tracing. See the CoreSight Cortex-M0+ Technical Reference Manual for more details on the Trace start and stop and for a detailed description of the MTB's MASTER register. The MTB can be programmed to stop tracing automatically when the memory fills to a specified watermark level or to start or stop tracing by writing directly to the MASTER.EN bit. If the watermark mechanism is not being used and the trace buffer overflows, then the buffer wraps around overwriting previous trace packets.

The base address of the MTB registers is 0x41006000; this address is also written in the CoreSight ROM Table. The offset of each register from the base address is fixed and as defined by the CoreSight MTB-M0+ Technical Reference Manual. The MTB has 4 programmable registers to control the behavior of the trace features:

- POSITION: Contains the trace write pointer and the wrap bit,
- MASTER: Contains the main trace enable bit and other trace control fields,
- FLOW: Contains the WATERMARK address and the AUTOSTOP and AUTOHALT control bits,
- BASE: Indicates where the SRAM is located in the processor memory map. This register is provided to enable auto discovery of the MTB SRAM location, by a debug agent.

See the CoreSight MTB-M0+ Technical Reference Manual for a detailed description of these registers.

The MTB has fixed QoS level 3 and the DSU has fixed QoS level 1.

The CPU QoS level can be written/read at address 0x41007110, bits [1:0]. Its reset value is 0x0.

Refer to different master QOSCTRL registers for configuring QoS for the other masters (USB, DMAC).

7.5 AHB-APB Bridge

The AHB-APB bridge is an AHB slave, providing an interface between the high-speed AHB domain and the low-power APB domain. It is used to provide access to the programmable control registers of peripherals.

AHB-APB bridge is based on AMBA APB Protocol Specification V2.0 (ref. as APB4) including:

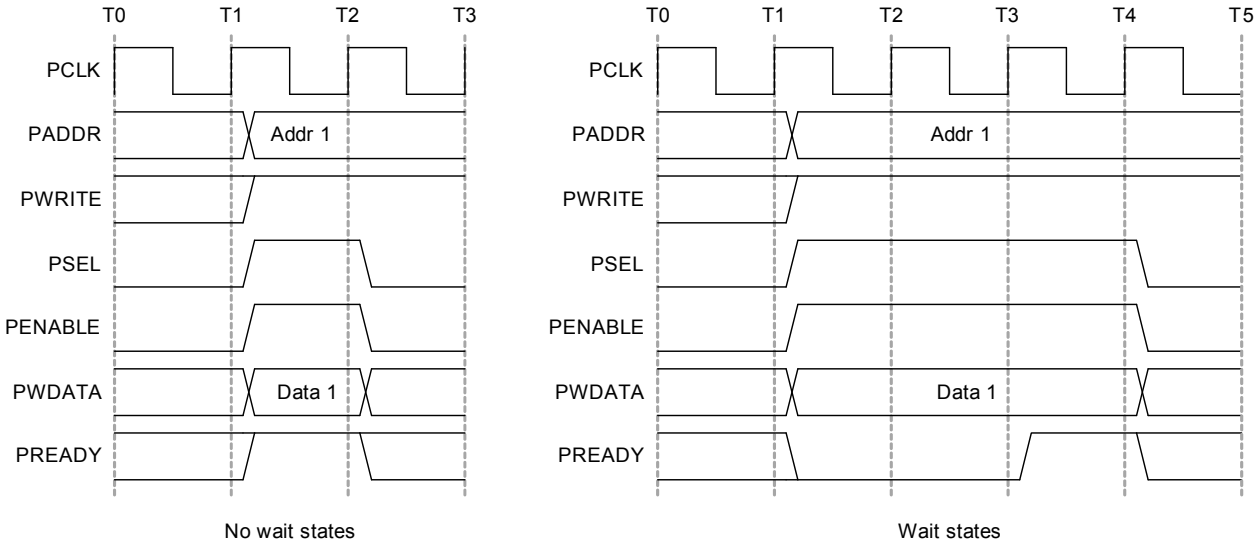
- Wait state support
- Error reporting
- Transaction protection
- Sparse data transfer (byte, half-word and word)

Additional enhancements:

- Address and data cycles merged into a single cycle
- Sparse data transfer also apply to read access

to operate the AHB-APB bridge, the clock (CLK_HPBx_AHB) must be enabled. See *PM – Power Manager* for details.

Figure 7-1. APB Write Access.



Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 3 – PORT
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 2 – NVMCTRL
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

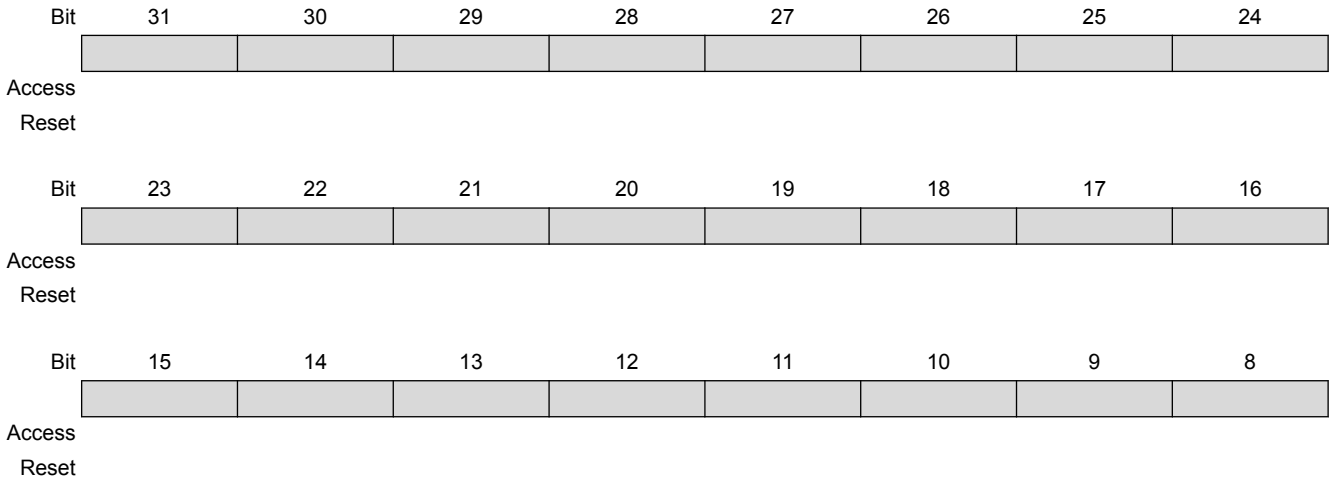
Bit 1 – DSU
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Write Protect Set

Name: WPSET
Offset: 0x04
Reset: 0x000002
Property: –



Property: –

Bit	31	30	29	28	27	26	25	24
Access								
Reset								

Bit	23	22	21	20	19	18	17	16
				I2S	PTC	DAC	AC	ADC
Access				R/W	R/W	R/W	R/W	R/W
Reset				0	0	0	0	0

Bit	15	14	13	12	11	10	9	8
	TC7	TC6	TC5	TC4	TC3	TCC2	TCC1	TCC0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Reset	0	0	0	0	0	0	0	0

Bit	7	6	5	4	3	2	1	0
	SERCOM5	SERCOM4	SERCOM3	SERCOM2	SERCOM1	SERCOM0	EVSYS	
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Reset	0	0	0	0	0	0	0	

Bit 20 – I2S
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 19 – PTC
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 18 – DAC:
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

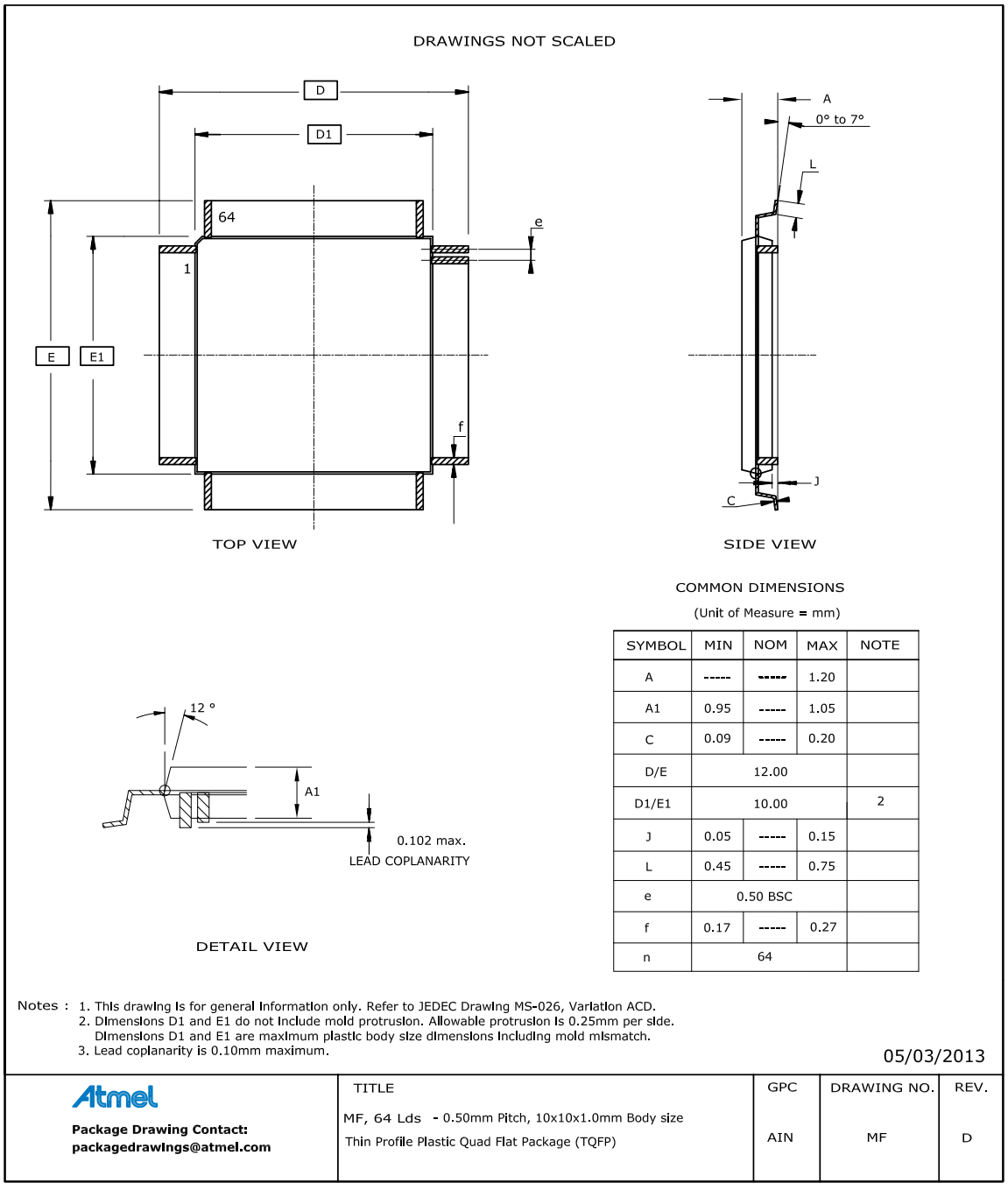
Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 17 – AC
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

8.2 Package Drawings

8.2.1 64 pin TQFP



COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	-----	-----	1.20	
A1	0.95	-----	1.05	
C	0.09	-----	0.20	
D/E		12.00		
D1/E1		10.00		2
J	0.05	-----	0.15	
L	0.45	-----	0.75	
e		0.50 BSC		
f	0.17	-----	0.27	
n		64		

Notes : 1. This drawing is for general information only. Refer to JEDEC Drawing MS-026, Variation ACD.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
3. Lead coplanarity is 0.10mm maximum.

05/03/2013

	TITLE	GPC	DRAWING NO.	REV.
Atmel **Package Drawing Contact:** **packagedrawings@atmel.com**	MF, 64 Lds - 0.50mm Pitch, 10x10x1.0mm Body size Thin Profile Plastic Quad Flat Package (TQFP)	AIN	MF	D

Table 8-2. Device and Package Maximum Weight

300	mg

Table 8-3. Package Characteristics

Moisture Sensitivity Level	MSL3

Table 8-5. Device and Package Maximum Weight

200	mg

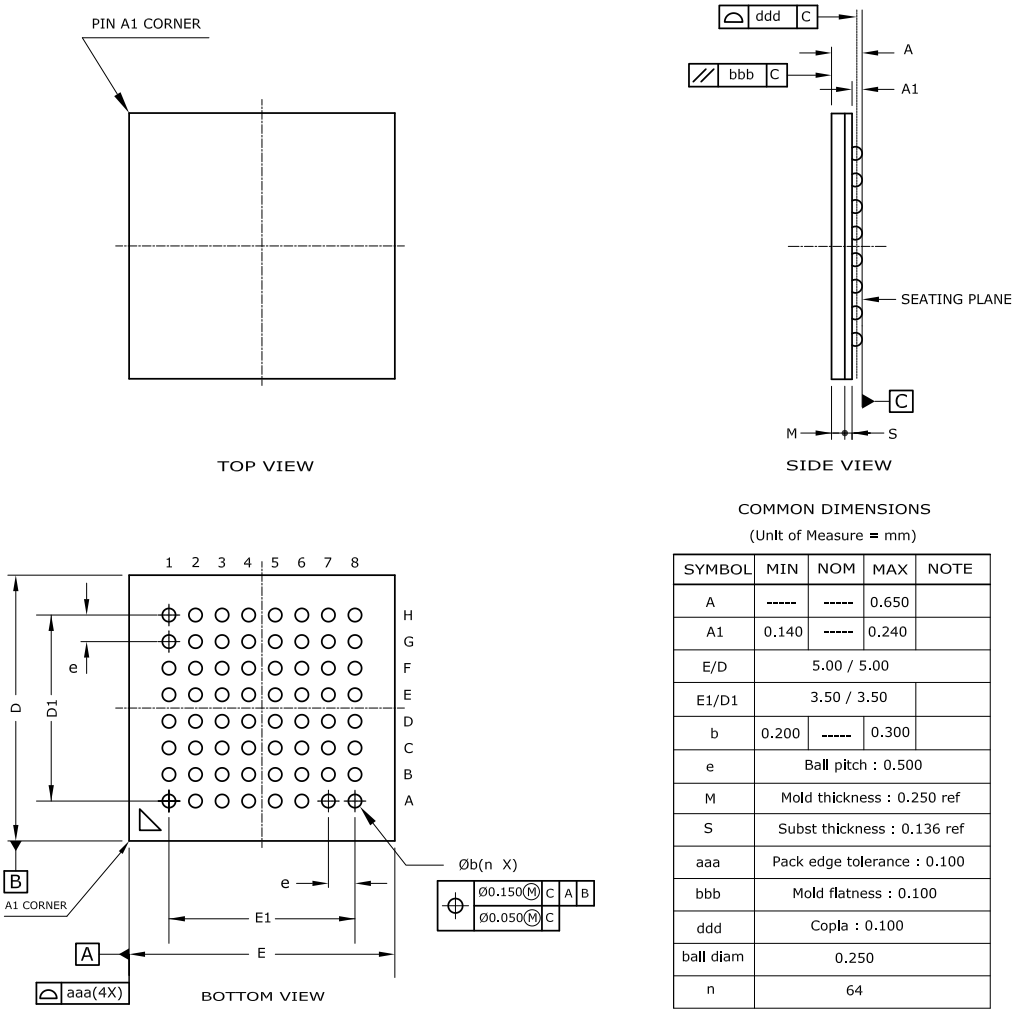
Table 8-6. Package Charateristics

Moisture Sensitivity Level	MSL3

Table 8-7. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E3

8.2.3 64-ball UFBGA



COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	-----	-----	0.650	
A1	0.140	-----	0.240	
E/D	5.00 / 5.00			
E1/D1	3.50 / 3.50			
b	0.200	-----	0.300	
e	Ball pitch : 0.500			
M	Mold thickness : 0.250 ref			
S	Subst thickness : 0.136 ref			
aaa	Pack edge tolerance : 0.100			
bbb	Mold flatness : 0.100			
ddd	Copla : 0.100			
ball diam	0.250			
n	64			

Notes : 1. This drawing is for general information only. Refer to JEDEC Drawing MO-280, Variation UCCBB for proper dimensions, tolerances, datums, etc.
2. Array as seen from the bottom of the package.
3. Dimension A includes stand-off height A1, package body thickness, and lid height, but does not include attached features.
4. Dimension b is measured at the maximum ball diameter, parallel to primary datum C.

Table 8-8. Device and Package Maximum Weight

27.4	mg

Table 8-11. Device and Package Maximum Weight

140	mg

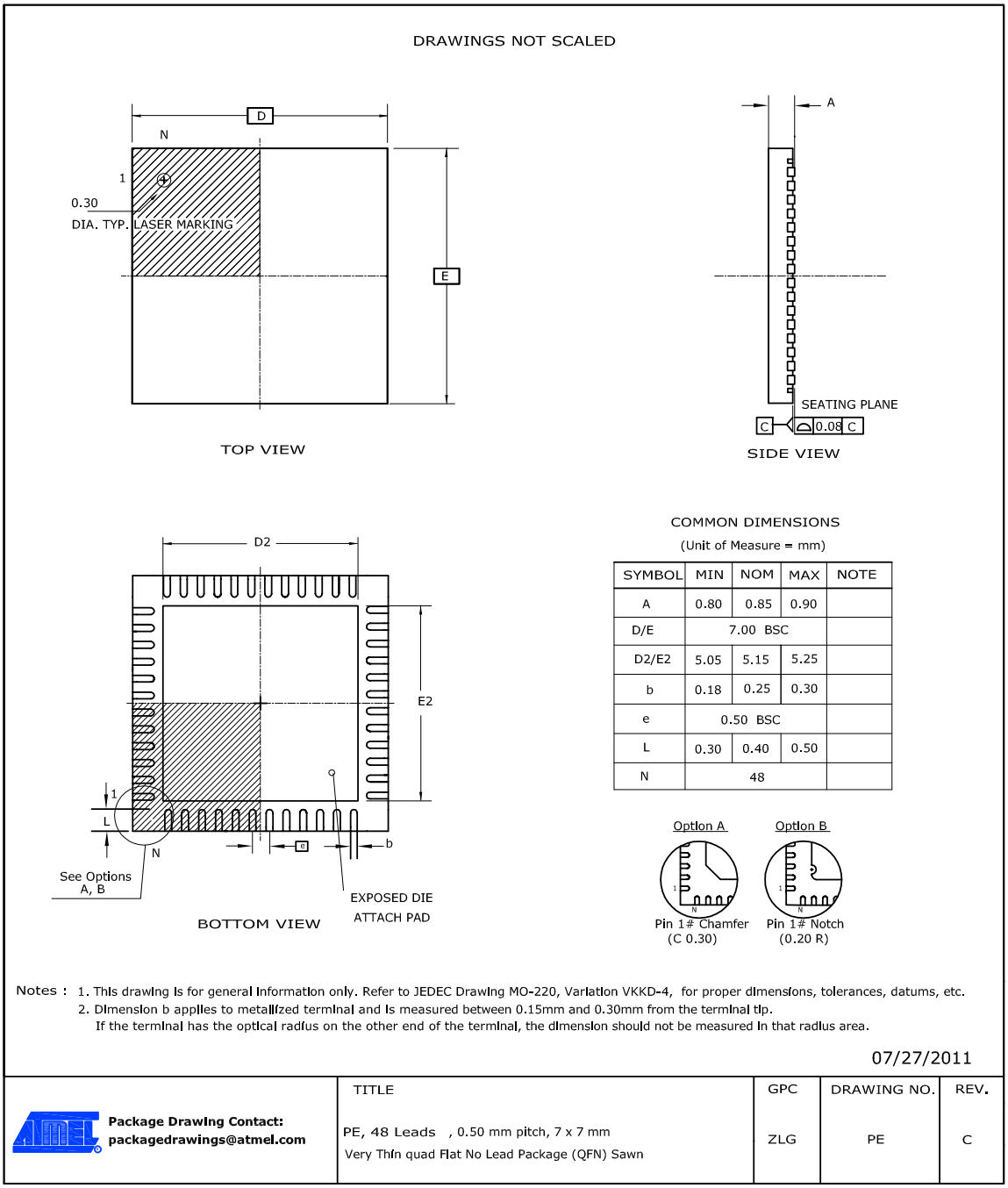
Table 8-12. Package Characteristics

Moisture Sensitivity Level	MSL3

Table 8-13. Package Reference

JEDEC Drawing Reference	MS-026
JESD97 Classification	E3

8.2.5 48 pin QFN



SYMBOL	MIN	NOM	MAX	NOTE
A	0.80	0.85	0.90	
D/E		7.00 BSC		
D2/E2	5.05	5.15	5.25	
b	0.18	0.25	0.30	
e		0.50 BSC		
L	0.30	0.40	0.50	
N		48		

Note: The exposed die attach pad is not connected electrically inside the device.

Table 8-14. Device and Package Maximum Weight

140	mg

Table 8-15. Package Characteristics

Moisture Sensitivity Level	MSL3

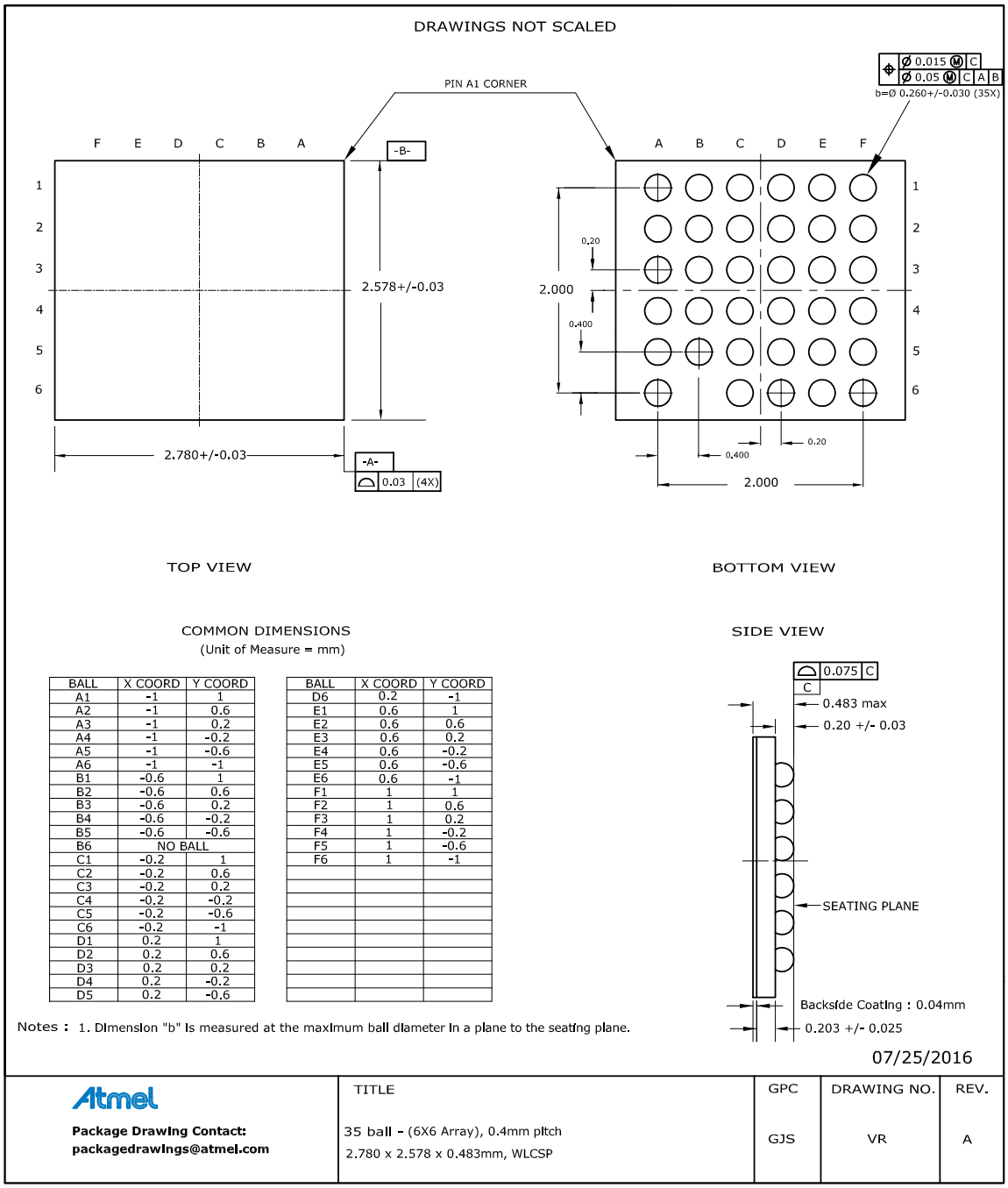
Table 8-27. Package Characteristics

Moisture Sensitivity Level	MSL1

Table 8-28. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E1

8.2.10 35 ball WLCSP (Device Variant C)



BALL	X COORD	Y COORD
A1	-1	1
A2	-1	0.6
A3	-1	0.2
A4	-1	-0.2
A5	-1	-0.6
A6	-1	-1
B1	-0.6	1
B2	-0.6	0.6
B3	-0.6	0.2
B4	-0.6	-0.2
B5	-0.6	-0.6
B6	NO BALL	
C1	-0.2	1
C2	-0.2	0.6
C3	-0.2	0.2
C4	-0.2	-0.2
C5	-0.2	-0.6
C6	-0.2	-1
D1	0.2	1
D2	0.2	0.6
D3	0.2	0.2
D4	0.2	-0.2
D5	0.2	-0.6

BALL	X COORD	Y COORD
D6	0.2	-1
E1	0.6	1
E2	0.6	0.6
E3	0.6	0.2
E4	0.6	-0.2
E5	0.6	-0.6
E6	0.6	-1
F1	1	1
F2	1	0.6
F3	1	0.2
F4	1	-0.2
F5	1	-0.6
F6	1	-1

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- **General Technical Support** – Frequently Asked Questions (FAQ), technical support requests, online discussion groups, Microchip consultant program member listing
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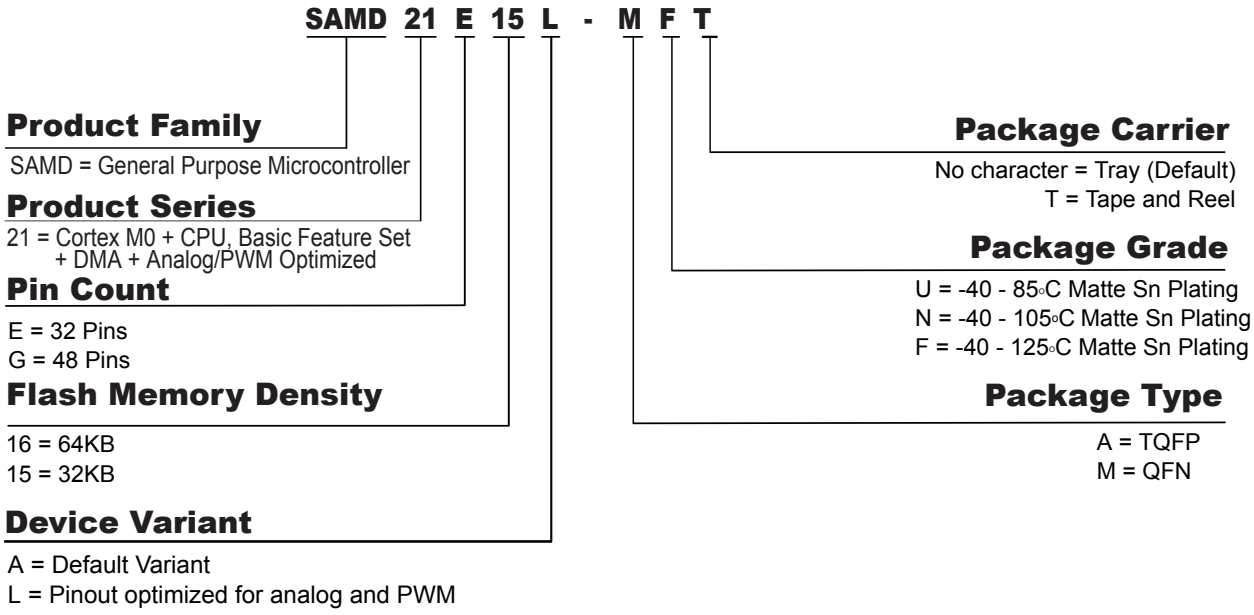

Note:

1. Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.
2. Small form-factor packaging options may be available. Please check http://www.microchip.com/packaging for small-form factor package availability, or contact your local Sales Office.

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